Amendments to the Claims:

The following listing of claims replaces all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A process for producing an organic-inorganic hybrid glassy material, the process comprising the sequential steps of:

producing a gel body by a sol-gel method in which at least one kind of a silicon alkoxide containing a phenyl group is used as a sol-gel raw material;

drying the gel body to obtain a dry gel;

melting the <u>dry</u> gel body by heating <u>at a temperature not lower than</u> softening temperature of the <u>dry gel</u> and not higher than 400°C into a melt; and

aging the melt at a temperature of from 30°C to 400°C for a period of time of 5 minutes or longer.

- 2. (Previously Presented) A process for producing an organic-inorganic hybrid glassy material as claimed in claim 1, wherein a structure of the gel body contains a unit represented by the formula of $Ph_nSiO_{(4-n)/2}$ where Ph represents a phenyl group and n represents a natural number selected from 1, 2 and 3.
- 3. (Canceled)
- 4. (Previously Presented) A process for producing an organic-inorganic hybrid glassy material as claimed in claim 1, wherein the melting step by heating is conducted at a temperature of from 30°C to 400°C.
- 5-22. (Canceled)
- 23. (Currently Amended) A process for producing an organic-inorganic hybrid glassy material, the process comprising the sequential steps of:

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producing a gel body by a sol-gel method in which at least one kind of a silicon alkoxide containing a phenyl group is used as a sol-gel raw material;

drying the gel body to obtain a dry gel;

mixing the <u>dry</u> gel body with a substance obtained by a non-aqueous acidbase reaction method to prepare a mixture;

melting the mixture by heating <u>at a temperature not lower than softening</u> temperature of the dry gel and not higher than 400°C into a melt; and

aging the melt at a temperature of from 30°C to 400°C for a period of time of 5 minutes or longer.

- 24. (Previously Presented) A process for producing an organic-inorganic hybrid glassy material as claimed in claim 23, wherein the gel body produced by the solgel method contains RSiO_{3/2} or R₂SiO, wherein R represents a phenyl group.
- 25. (Previously Presented) A process for producing an organic-inorganic hybrid glassy material as claimed in claim 23 or 24, wherein the substance obtained by the non-aqueous acid-base reaction method contains R_2SiO , wherein R_2SiO , wherein
- 26. (Previously Presented) A process for producing an organic-inorganic hybrid glassy material as claimed in claim 23, wherein the melting step by heating is conducted at a temperature of from 30°C to 400°C.

27-29. (Canceled)

30. (Currently Amended) A process for producing an organic-inorganic hybrid glassy material, the process comprising the sequential steps of:

producing a gel body by a sol-gel method in which a phenyltrialkoxysilane and a second silane are used as sol-gel raw materials, wherein the second silane is selected from the group consisting of alkylalkoxysilanes and diphenyldialkoxysilanes;

drying the gel body to obtain a dry gel;

melting the <u>dry</u> gel body by heating <u>at a temperature not lower than softening temperature of the dry gel and not higher than 400°C into a melt; and aging the melt at a temperature of from 30°C to 400°C for a period of time of 5 minutes or longer.</u>

- 31. (Previously Presented) A process according to claim 30, wherein:
 the phenyltrialkoxysilane is phenyltriethoxysilane; and
 the diphenyldialkoxysilane is diphenyldiethoxysilane or the
 alkylalkoxysilane is selected from the group consisting of methyltriethoxysilane,
 dimethyldiethoxysilane, diethyldiethoxysilane, and ethyltriethoxysilane.
- 32. (Previously Presented) A process according to claim 30, wherein: the phenyltrialkoxysilane is phenyltriethoxysilane; and the second silane is a dialkyldialkoxysilane.
- 33. (Previously Presented) A process according to claim 32, wherein the dialkyldialkoxysilane is dimethyldiethoxysilane or diethyldiethoxysilane.
- 34. (Previously Presented) A process according to claim 30, wherein: the phenyltrialkoxysilane is phenyltriethoxysilane; and the second silane is a diphenyldialkoxysilane.
- 35. (Previously Presented) A process according to claim 34, wherein the diphenyldialkoxysilane is diphenyldiethoxysilane.